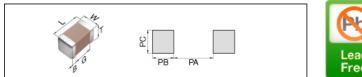


Creation Date: September 04, 2016

## C2012X6S1C226M125AC (TDK item description: C2012X6S1C226MT\*\*\*\*)







Size		
Length(L)	2.00mm +/-0.20mm	
Width(W)	1.25mm +/-0.20mm	
Thickness(T)	1.25mm +/-0.20mm	
Terminal Width(B)	0.20mm Min.	
Terminal Spacing(G)	0.50mm Min.	
Recommended Land Pattern(PA)	1.00 to 1.30mm (Flow Soldering) < br /> 0.90 to 1.20mm (I	Reflow Soldering)
Recommended Land Pattern(PB)	1.00 to 1.20mm (Flow Soldering) br />0.70 to 0.90mm (I	Reflow Soldering)
Recommended Land Pattern(PC)	0.80 to 1.10mm (Flow Soldering) < br /> 0.90 to 1.20mm (I	Reflow Soldering)
Recommended Slit Pattern(SD)		

Electrical Characteristics		
Capacitance	22uF +/-20%	
Rated Voltage	16Vdc	
Temperature Characteristic	X6S(+/-22%)	
Dissipation Factor	10% Max.	
Insulation Resistance	4MΩ Min.	

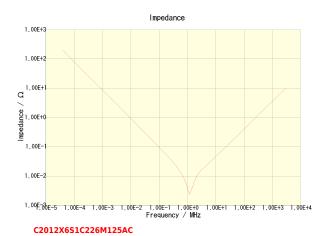
Other		
Soldering Method	Reflow, Flow	
AEC Q200	No	
Packing	Blister (Plastic)Taping [180mm Reel]	
Package Quantity	2000Pcs Min.	

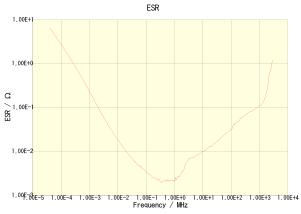
<sup>•</sup>This PDF document was created based on the data listed on the TDK Corporation website.

<sup>•</sup>All specifications are subject to change without notice.

Creation Date: September 04, 2016 C2012X6S1C226M125AC

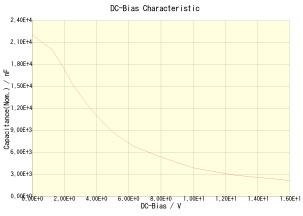
## Characteristic Graphs (This is reference data, and does not guarantee the product's characteristics.)



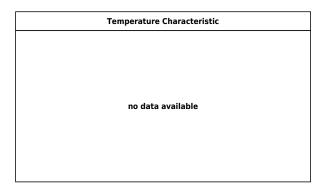


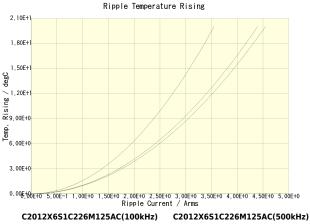
C2012X6S1C226M125AC





C2012X6S1C226M125AC





C2012X6S1C226M125AC(1MHz)

<sup>•</sup>This PDF document was created based on the data listed on the TDK Corporation website.

<sup>•</sup>All specifications are subject to change without notice.